

# W-GM-4200

## Wafer Edge Grinding Machine

- Best Seller Machine W-GM-Series
- Improve the Space Efficiency by the Compact Design
- Highly Accurate Grinding by the Synchronized X · Y ·  $\theta$  Support Control
- Easy Operation by Touch Panel
- Measuring of Grinding Result and Automatic Correction



TOKYO SEIMITSU CO., LTD.

## Specification of W-GM-4200

Basic Specification		
Wafer Size		$\phi 2'' \sim \phi 6'' / \phi 4'' \sim \phi 8''$
Wafer Thickness		0.4 ~ 1.0mm (Standard)
Wafer Type		OF, CF $\times 2$ (<1/2 OF), Notch (Option)
Grinding Unit		2-stage
Periphery Grinding Wheel	OD (Groove)	$\phi 200\text{mm}$
	OD (Periphery)	$\phi 202\text{mm}$
	ID	$\phi 30\text{mm}$
	Flange Thickness	20mm
Spindle frequency ( $\phi 202$ )		4000rpm
Grinding Speed		Periphery, OF and notch can be set individually
Periphery Grinding Spindle		$\phi 5 \sim \phi 8$ : Built-in motor
		$\phi 2 \sim \phi 6$ : Belt drive by magnet motor
Operation Panel		12" color LCD panel with touch sensor
Signal Tower		3-color Indicator
Dimensions		2115 (W) x 1410 (D) x 2000 (H) mm
Weight		Approx. 3000kg
Mechanical Specification		
Grinding Table X, Y, Z-axis	Resolution	1 $\mu\text{m}$
Grinding Table $\theta$ -axis	Resolution	0.001°
	Driving System	AC Servo Motor etc
Transfer Unit	Loading System	Chuck Loading (Upper Surface)
Cleaning Unit	Cleaning System	Spin Cleaning
	Drying System	Dry Air
Loader Unit	Type	Cassette Carrier Type
	Number of Cassette	4C
Measuring Unit Specification		
Wafer Thickness Measurement	Resolution	1 $\mu\text{m}$
	Repeatability	Within $\pm 2 \mu\text{m}$
	Accuracy	
	Measuring Type	Contact Type or Non Contact Type
	Measuring Equipment	Contact Type: Accretech MINIAX (Moire Scale)
		Non Contact Type: Accretech CADICOM
Non-contact Alignment System	Type	Laser System
	Resolution	1 $\mu\text{m}$
	Centering Accuracy	Within $\pm 50 \mu\text{m}$

